



# TB-03F SPECIFICATION

Version V1.0

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## 1.PRODUCT DESCRIPTION

TB-03F intelligent lighting module is a Bluetooth module designed based on the TLSR8253 chip and conforming to BT 5.0 low power Tmall Genie Mesh. This module supports the direct control of Tmall Genie and has the Bluetooth mesh networking function. The devices are peered through Star network communication, using Bluetooth broadcast for communication, can ensure timely response in the case of multiple devices. This module is applied to intelligent light control, which can meet the requirements of low power consumption, low latency and short-range wireless data communication.

### Features

- Can be directly controlled by Tmall Elf without a gateway
- SMD-22 package
- 6 PWM outputs
- With on-board antenna, no need to design antenna
- Brightness (duty cycle) adjustment range 5% -100%
- Factory default 50% duty cycle for cool and warm colors
- PWM output frequency 1KHz
- Support multiple sleep modes, deep sleep current as low as 0.4uA
- With wall switch to switch color temperature function
- Support secondary development

## Main parameters

**List 1 Main parameter description**

<b>Module model</b>	TB-03F
<b>Dimension</b>	24*16*3( $\pm 0.2$ )MM
<b>Package</b>	SMD-22
<b>Wireless standard</b>	BT 5.0
<b>Frequency range</b>	2400 ~ 2483.5MHz
<b>Transmit power</b>	Maximum 10dBm
<b>Receive sensitivity</b>	-93dBm $\pm 2$
<b>Interface</b>	GPIO/PWM/SPI/ADC/I2S
<b>Operating temperature</b>	-20°C ~ 70 °C
<b>Storage environment</b>	-40 °C ~ 125 °C , < 90%RH
<b>Power supply range</b>	Voltage 2.7V ~ 3.6V, current $\geq 50$ mA
<b>Power consumption</b>	deep sleep mode: 0.4uA
	Standby mode: 2.51mA
	TX(PRBS9)@10dBm:6.36mA
	TX(CarrierData)@10dBm:20.54mA
<b>Transmission distance</b>	Open Line of Sight: 80m ~ 150m

## 2.ELECTRICAL PARAMETERS

### Electrical characteristics

#### Absolute Maximum Rating

*Any damage exceeding the following absolute maximum ratings may cause chip damage*

Item	Min	Typical	Max	Unit
Power supply voltage	2.7	3.3	3.6	V
I/O voltage (VCCIO)	-0.3	-	3.6	V
Operating temperature	-20	-	+70	°C
Storage temperature	-40	-	+125	°C

#### Power consumption

Item	Typical	Unit
Transmit power (10dBm)	20.54	mA
Receive power	6.36	mA
Standby power consumption	2.51	mA
Light sleep	1.5	uA
Deep sleep	0.4	uA

## RF Parameters

### Transmit power

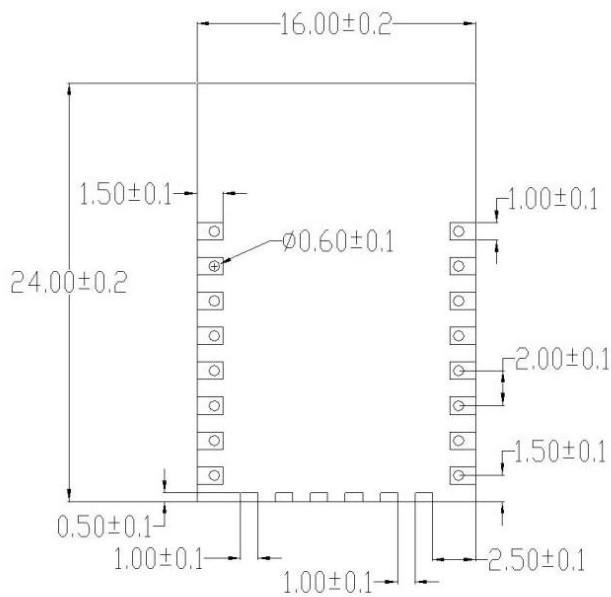
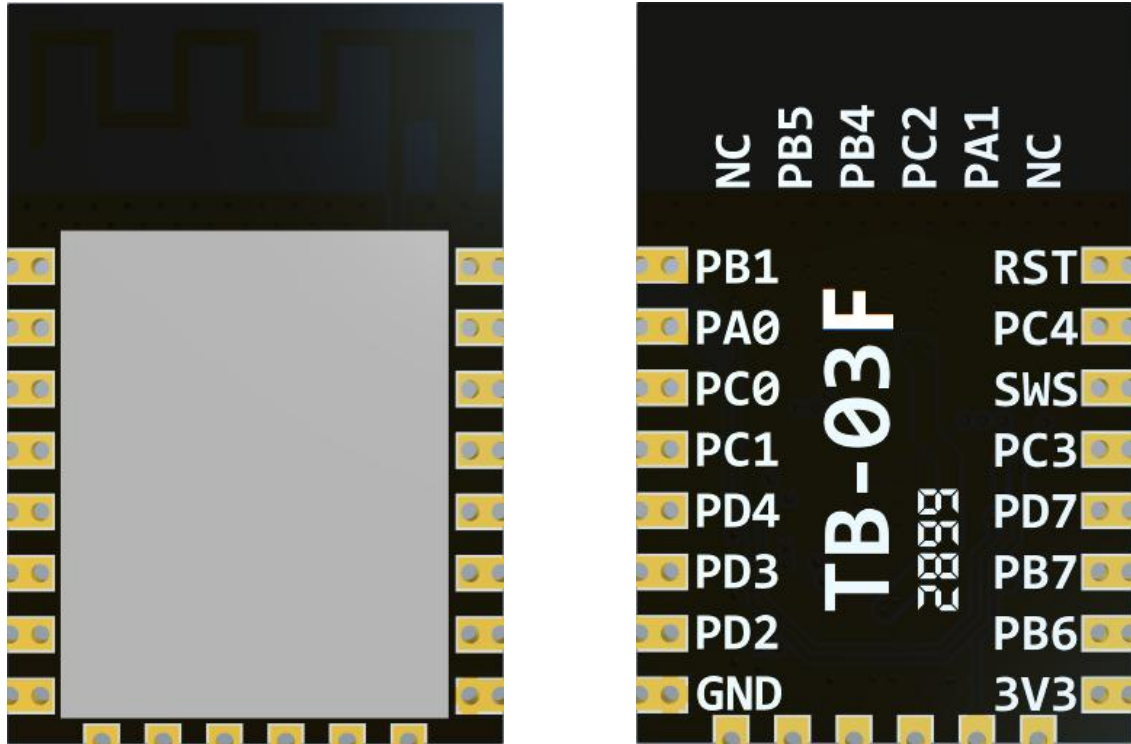
Item	Min	Typical	Max	Unit
Average power	-	9.5	10	dBm

### Receive sensitivity

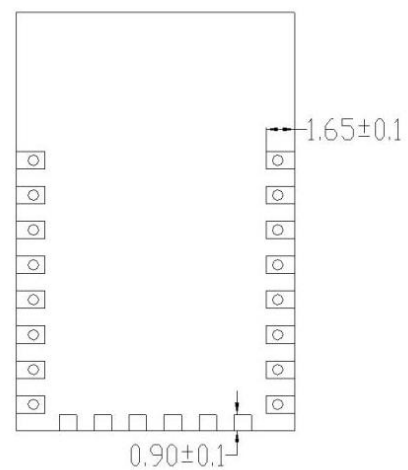
Item	Min	Typical	Max	Unit
Receive sensitivity	-94	-93	-	dBm



### 3. PHYSICAL DIMENSION



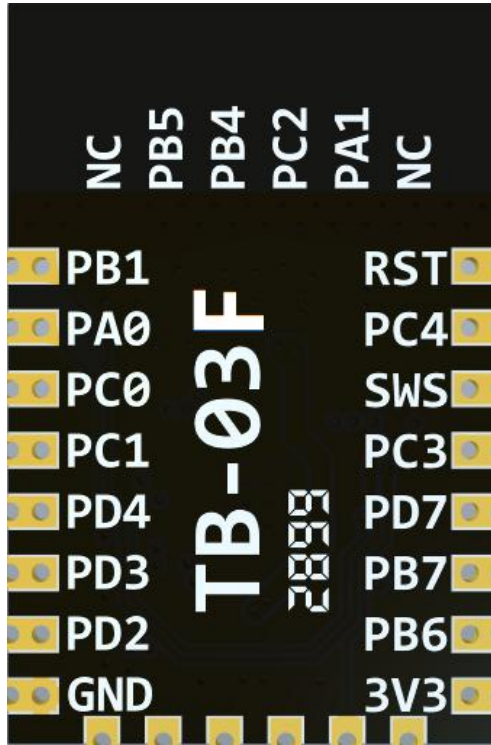
正面



背面

## 4. PIN DEFINITION

The TB-03F module has a total of 22 interfaces. For example, the pin diagram, the pin function definition table is the interface definition.



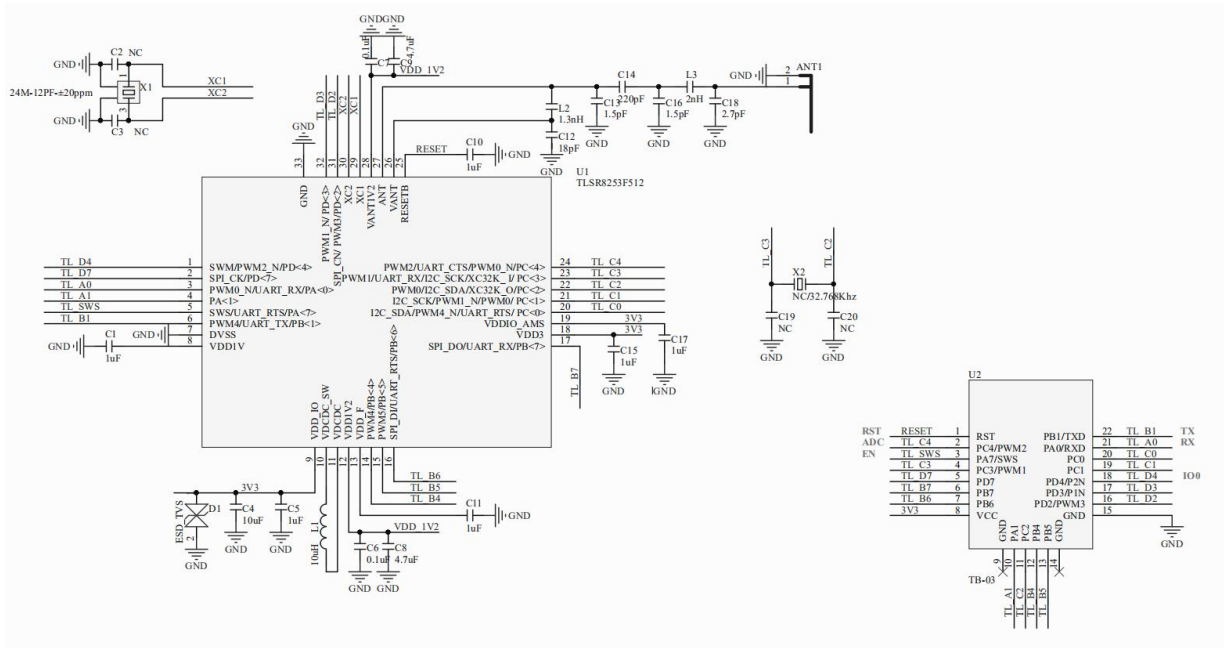
TB-03F PIN diagram

PIN definition list

No.	Name	Function description
1	RST	Reset active low
2	PC4	PWM2 output/UART_CTS/PWM0 Inverted output/SAR ADC input /GPIO PC4
3	SWS	Single line slave/UART_RTS/GPIO PA7
4	PC3	PWM1 output/UART_RX/I2C Serial clock/32kHz Crystal input (optional)/GPIO PC3
5	PD7	GPIO PD7/SPI clock (I2C_SCK)
6	PB7	SPI_DO Data output/UART_RX/SAR ADC input/GPIO PB7
7	PB6	SPI_DI data input (I2C_SDA) /UART_RTS/SAR ADC input/GPIO PB6

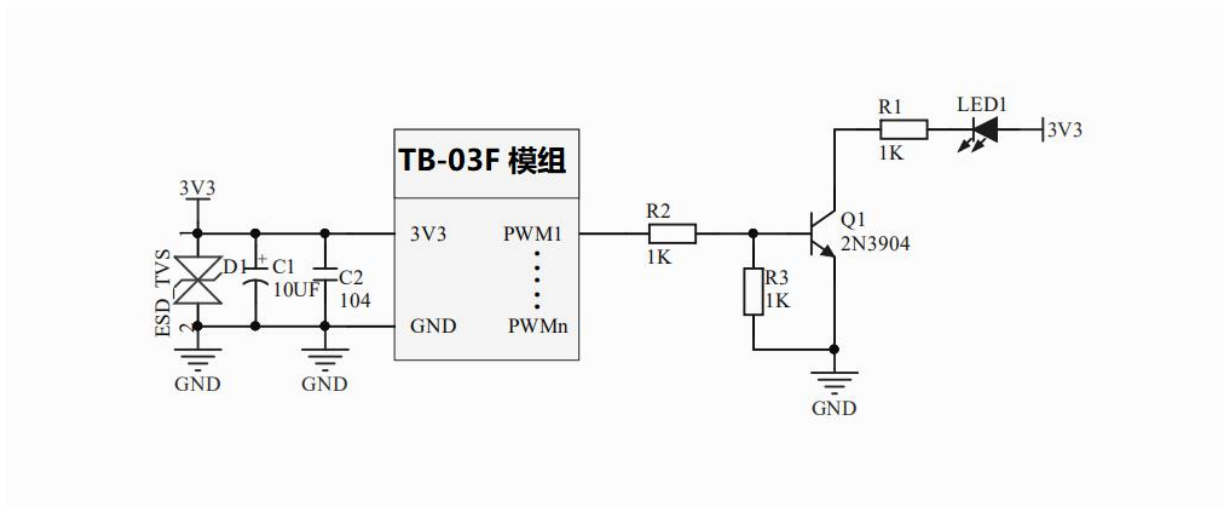
8	3V3	Power supply
9	NC	Blank
10	PA1	GPIO PA1/ I2S_clock
11	PC2	PWM0 output/I2C serial data/32kHz Crystal output (optional) /GPIO PC2
12	PB4	PWM4 output/SAR ADC input/GPIO PB4
13	PB5	PWM5 output/SAR ADC input/GPIO PB5
14	NC	Blank
15	GND	Ground
16	PD2	GPIO PD2/PWM3 output/SPI Chip selection (active low)/I2S_LR
17	PD3	GPIO PD3/PWM1 Inverted output/I2S_SDI
18	PD4	GPIO PD4/Single line host SWM/PWM2 Inverted output/I2S_SDO
19	PC1	I2C_CLK/PWM1 Inverted output/PWM0 output/GPIO PC1
20	PC0	I2C_SDA/PWM4 Inverted output/UART_RTS /GPIO PC0
21	PA0	UART_RX/GPIO PA0/PWM0 Inverted output
22	PB1	UART_TX/GPIO PB1/PWM4 output/SAR ADC input

## 5. SCHEMATIC



## 6. DESIGN GUIDE

### 1、Application circuit



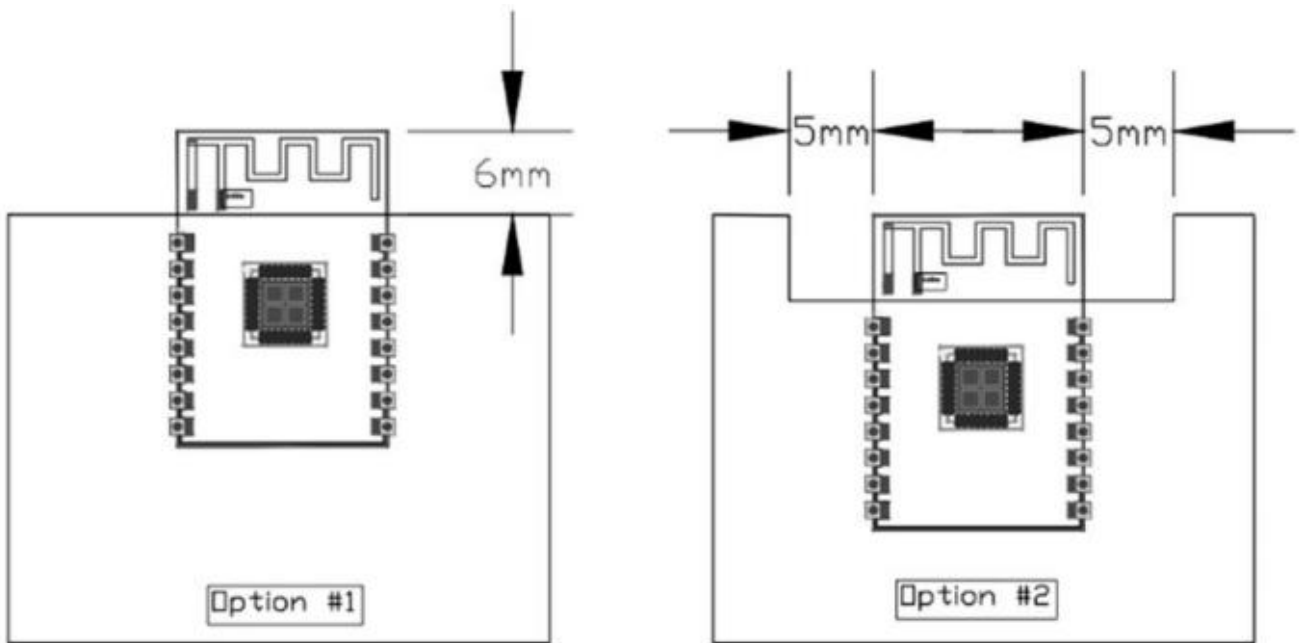
### 2、Antenna layout requirements

(1) For the installation position on the motherboard, the following two methods are recommended:

Solution 1: Place the module on the edge of the motherboard, and the antenna area extends beyond the edge of the motherboard.

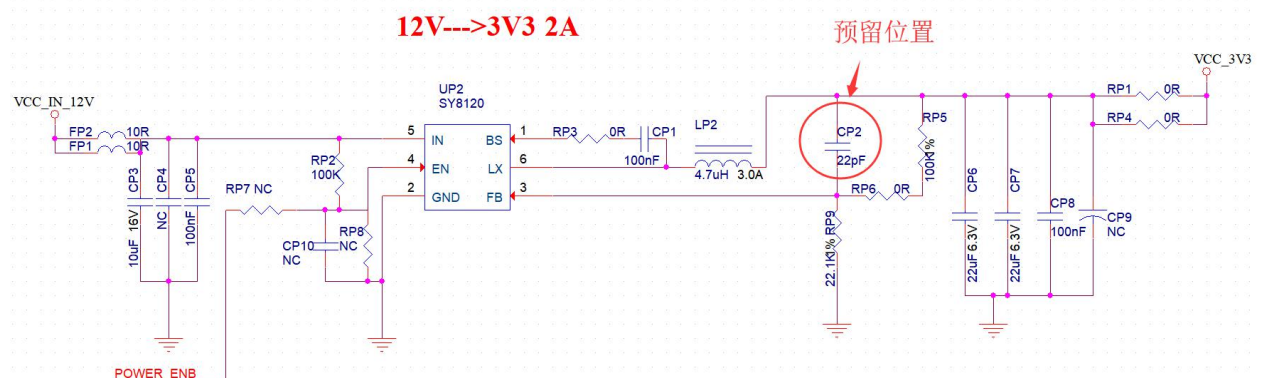
Solution 2: Place the module on the edge of the motherboard, and the edge of the motherboard hollows out an area at the antenna position.

(2) In order to meet the performance of the on-board antenna, it is forbidden to place metal parts around the antenna and keep it away from high-frequency devices.



### 3、Power supply

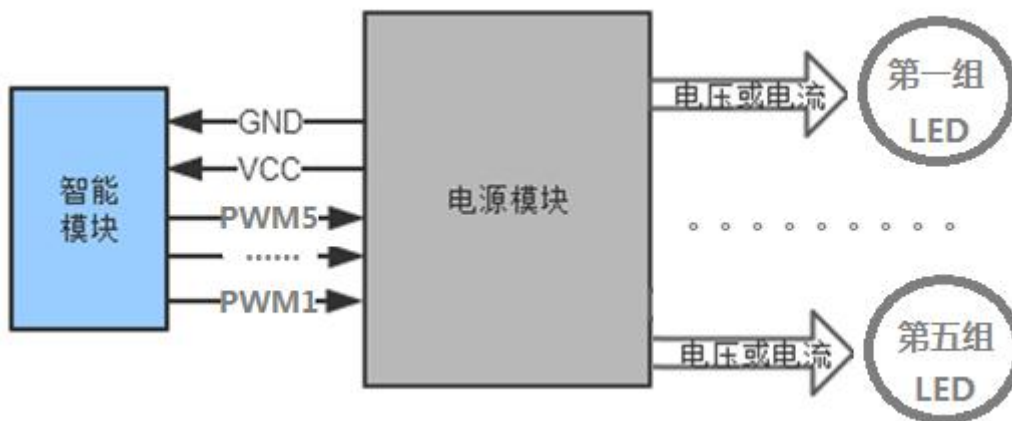
- (1) Recommended 3.3V voltage, peak current above 50mA
- (2) It is recommended to use LDO power supply; if DC-DC is used, it is recommended that the ripple be controlled within 30mV.
- (3) The DC-DC power supply circuit is recommended to reserve the position of the dynamic response capacitor, which can optimize the output ripple when the load changes greatly.
- (4) 3.3V power interface is recommended to add ESD devices.



### 4、Design description of PWM dimming scheme

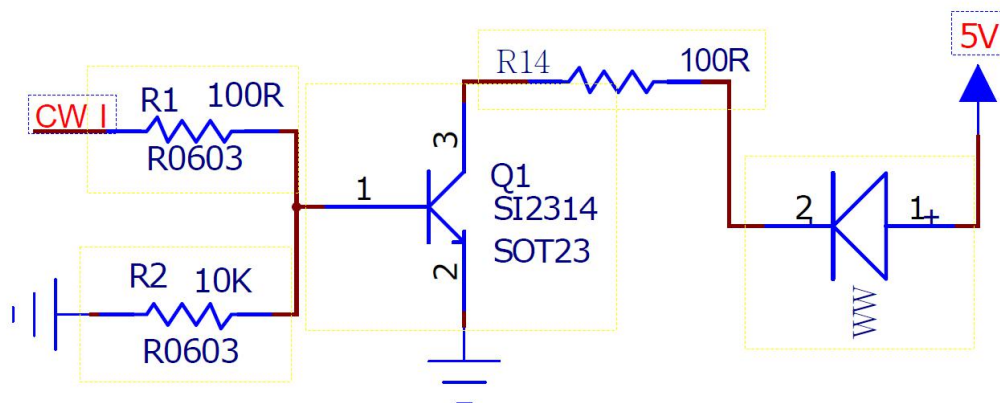
For lamps that require dimming, you only need to connect the PWM pins of the corresponding color to the control end of the driving circuit of the subsequent stage; the PWM independently outputs a digital signal with a 100-level adjustable duty cycle, and the latter circuit can be a voltage The driving type may be a current driving type.

#### Connection diagram



### 5、LED Drive Reference Design

TB-03F module application only needs 3.3V power supply and simple driving circuit to achieve intelligent light control. Take MOS tube to drive a channel of white light as an example, the design reference is as follows; CW\_I is the module's positive white light PWM output pin , Q1 is MOS tube, WW is LED lamp bead, the other 4 road lamp driving circuit is the same as this road design method.



### 6、SECENDORY DEVELOPMENT

The TB-03F module supports users to write firmware programs to achieve customized functions.

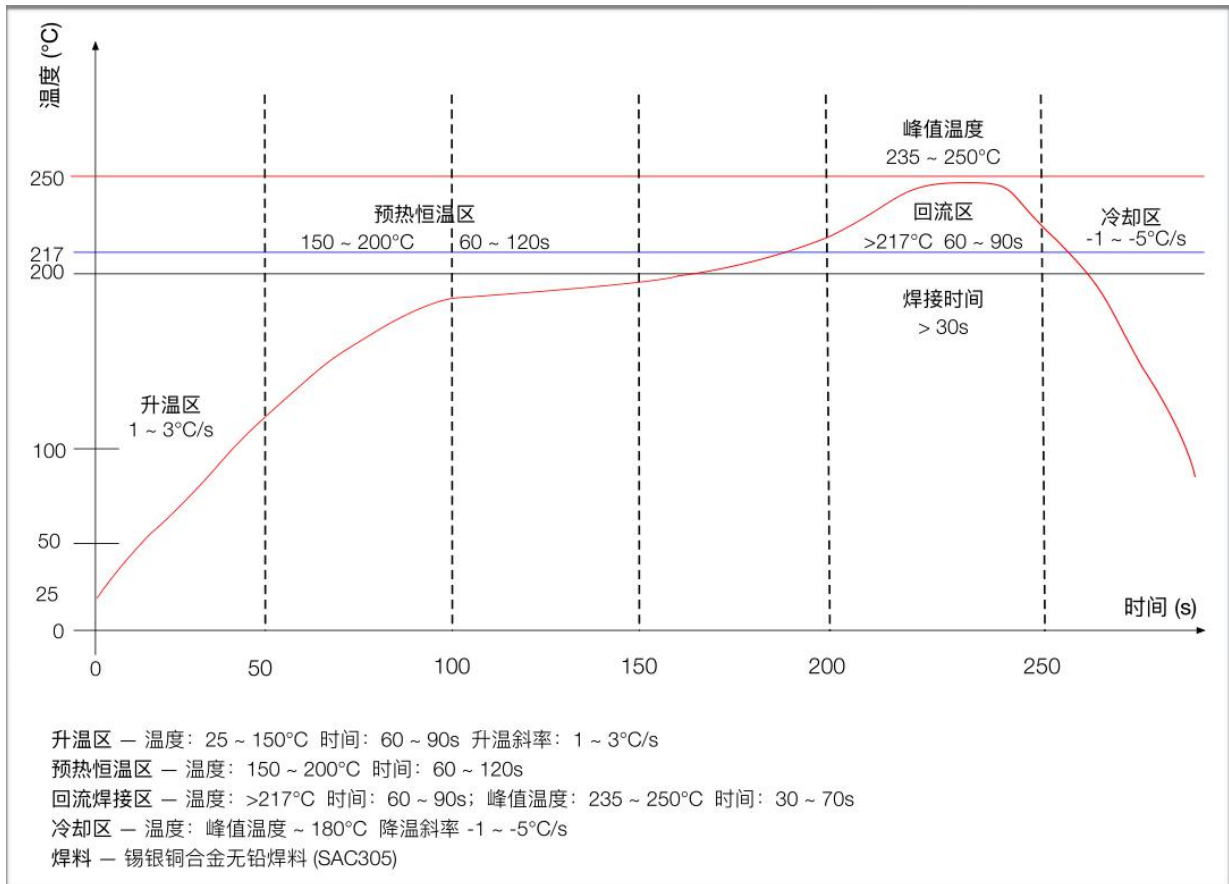
If you use a Linux machine to develop the firmware, you can refer to the SDK, documentation and source address of Anxin's collation:

[https://github.com/Ai-Thinker-Open/Telink\\_825X\\_SDK](https://github.com/Ai-Thinker-Open/Telink_825X_SDK).

If you use Windows development, please refer to the original SDK provided by the chip manufacturer, download address:

<http://wiki.telink-semi.cn>

## 7. REFLOW PROFILE





## 8.PACKAGING

As shown in the figure below, the packaging of TB-03F is taping packaging.



## 9.CONTACT US

Official website: <https://www.ai-thinker.com>

Development DOCS: <https://docs.ai-thinker.com>

Official forum: <http://bbs.ai-thinker.com>

Sample purchase: <https://anxinke.taobao.com>

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